

Dual N-Channel Enhancement Mode MOSFET

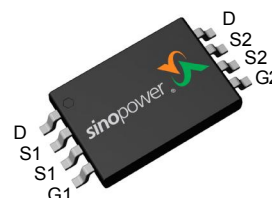
Features

- 20V/9A,
 $R_{DS(ON)} = 9.5m\Omega(max.) @ V_{GS} = 4.5V$
 $R_{DS(ON)} = 10m\Omega(max.) @ V_{GS} = 4V$
 $R_{DS(ON)} = 10.5m\Omega(max.) @ V_{GS} = 3.7V$
 $R_{DS(ON)} = 11.5m\Omega(max.) @ V_{GS} = 3.1V$
 $R_{DS(ON)} = 13m\Omega(max.) @ V_{GS} = 2.5V$
- Reliable and Rugged
- ESD Protected
- Lead Free and Green Devices Available (RoHS Compliant)

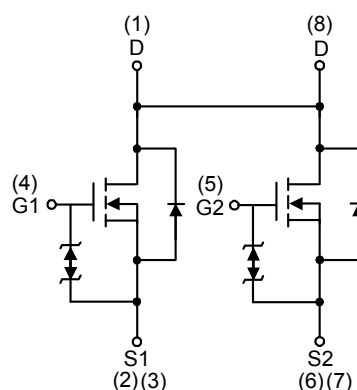
Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

Pin Description



Top View of TSSOP-8



N-Channel MOSFET

Ordering and Marking Information

SM9994DS □□-□□□ □□□□□□□□ Assembly Material Handling Code Temperature Range Package Code	Package Code O : TSSOP-8 Operating Junction Temperature Range C : -55 to 150 °C Handling Code TR : Tape & Reel (4000ea/reel) Assembly Material G : Halogen and Lead Free Device
SM9994DS O :	SM9994 XXXXX XXXXXX - Lot Code

Note : SINOPOWER lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. SINOPOWER lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. SINOPOWER defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

SINOPOWER reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Rating	Unit
Common Ratings				
V _{DSS}	Drain-Source Voltage		20	V
V _{GSS}	Gate-Source Voltage		±12	
I _D	Continuous Drain Current	T _A =25°C	9	A
		T _A =70°C	7.5	
I _{DM}	Continuous Drain Current	T _A =25°C	36	A
I _S	Diode Continuous Forward Current		2	A
T _J	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-55 to 150	
P _D	Maximum Power Dissipation	T _A =25°C	1.25	W
		T _A =70°C	0.8	
R _{θJA} ^a	Thermal Resistance-Junction to Ambient	t ≤ 10s	100	°C/W

Note a : Surface Mounted on 1in^2 pad area , $t \leq 10\text{s}$

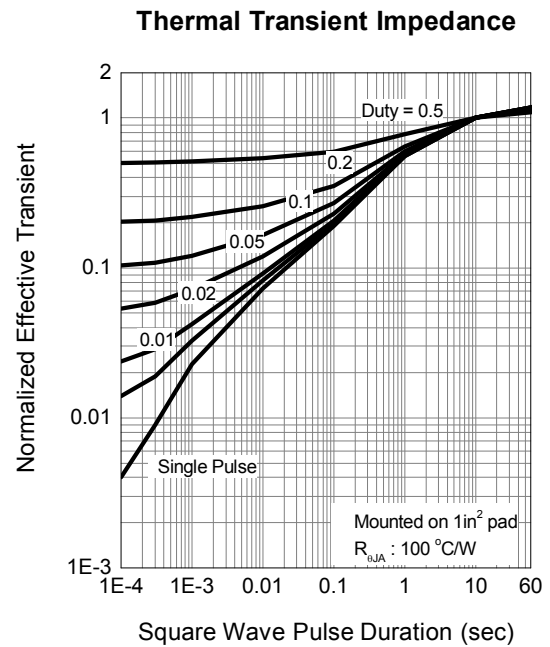
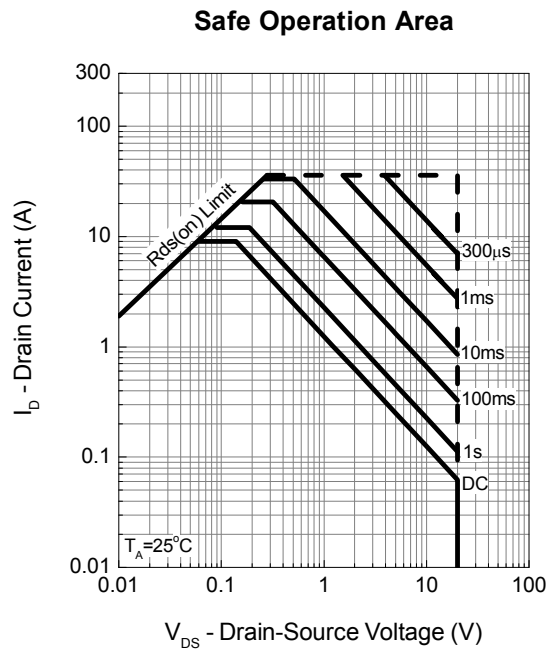
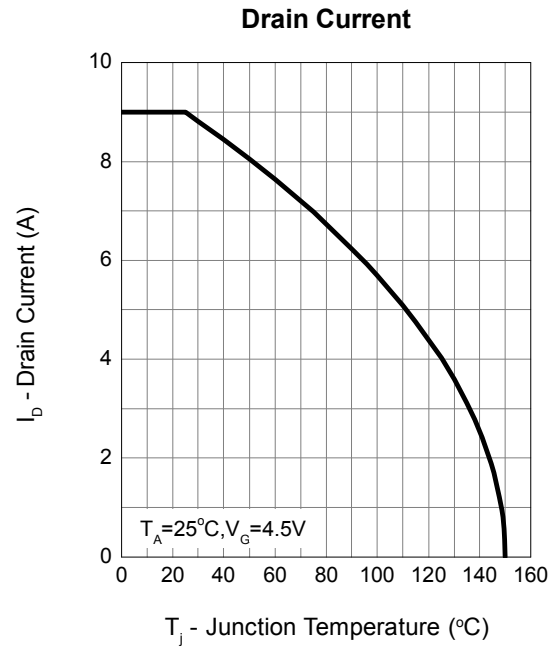
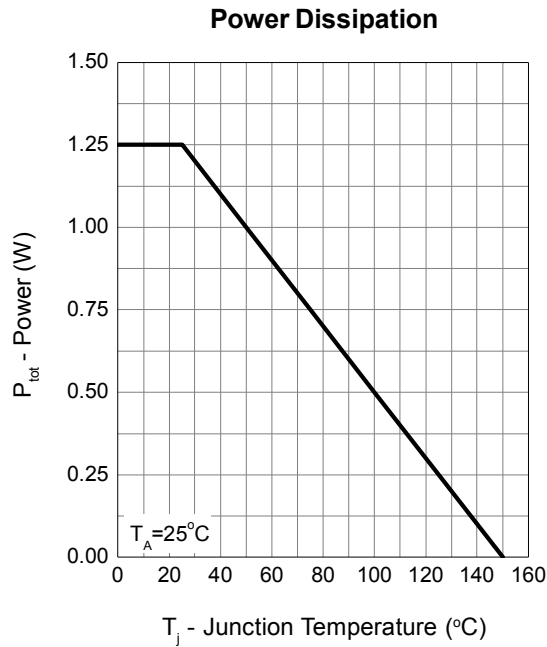
Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =16V, V _{GS} =0V T _J =85°C	- -	- -	1 30	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	0.5	0.7	1	V
I _{GSS}	Gate Leakage Current	V _{GS} =±12V, V _{DS} =0V	-	-	±10	μA
R _{DS(ON)} ^b	Drain-Source On-state Resistance	V _{GS} =4.5V, I _{DS} =9A	-	7.6	9.5	mΩ
		V _{GS} =4V, I _{DS} =8A	-	7.8	10	
		V _{GS} =3.7V, I _{DS} =7A	-	8	10.5	
		V _{GS} =3.1V, I _{DS} =6A	-	8.5	11.5	
		V _{GS} =2.5V, I _{DS} =5A	-	9.5	13	
Diode Characteristics						
V _{SD} ^b	Diode Forward Voltage	I _{SD} =2A, V _{GS} =0V	-	0.8	1.3	V
t _{rr}	Reverse Recovery Time	I _{SD} =5.5A, dI _{SD} /dt=100A/μs	-	36.5	-	ns
Q _{rr}	Reverse Recovery Charge		-	30	-	nC
Dynamic Characteristics ^c						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	1.5	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, Frequency=1.0MHz	-	2000	-	pF
C _{oss}	Output Capacitance		-	370	-	
C _{rss}	Reverse Transfer Capacitance		-	350	-	
t _{d(ON)}	Turn-on Delay Time		V _{DD} =10V, R _L =10Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	13	24
t _r	Turn-on Rise Time	-		16	28.5	
t _{d(OFF)}	Turn-off Delay Time	-		40	75	
t _f	Turn-off Fall Time	-		6	11	
Gate Charge Characteristics ^c						
Q _g	Total Gate Charge	V _{DS} =10V, V _{GS} =4.5V, I _{DS} =9A	-	27	-	nC
Q _{gs}	Gate-Source Charge		-	2.5	-	
Q _{gd}	Gate-Drain Charge		-	11.8	-	

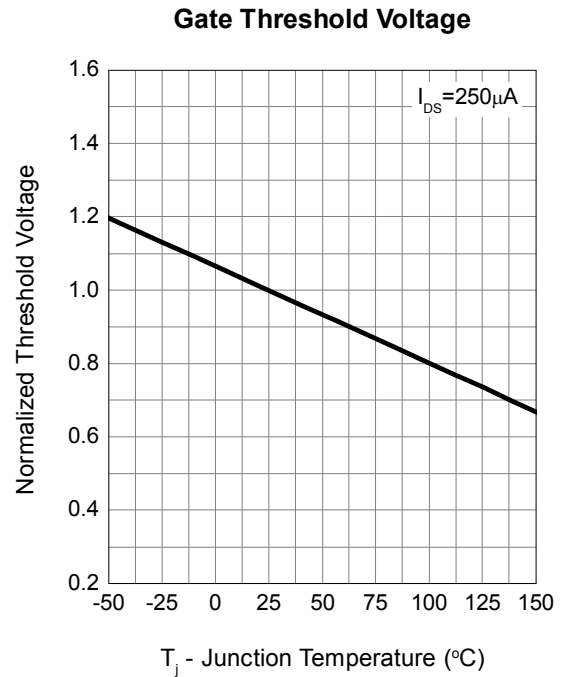
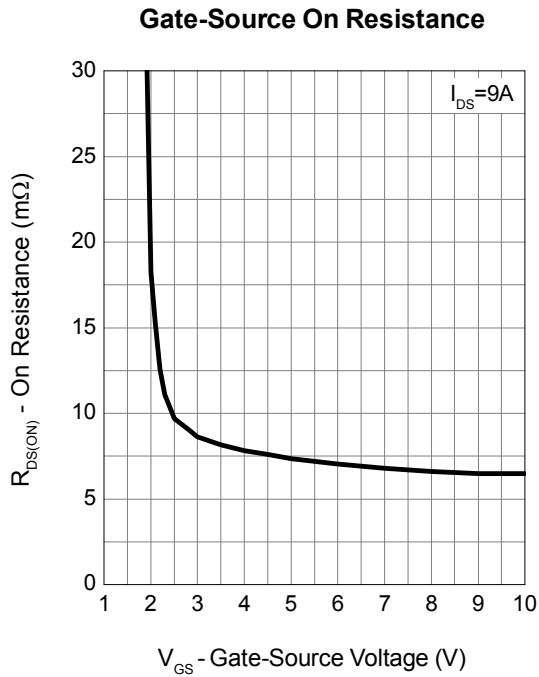
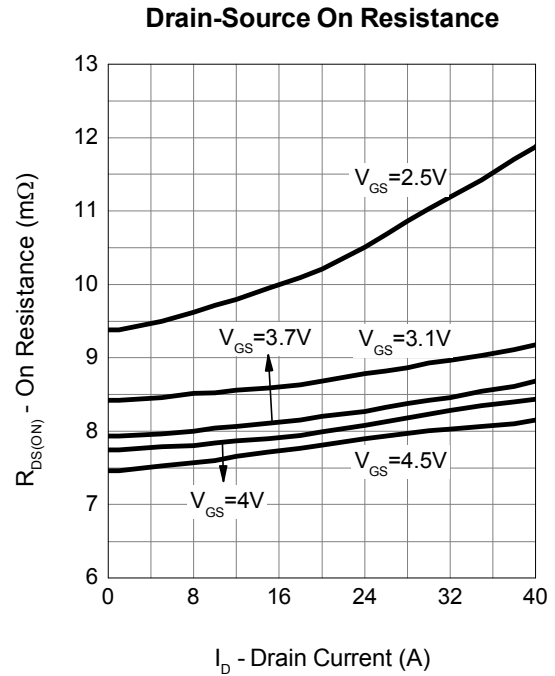
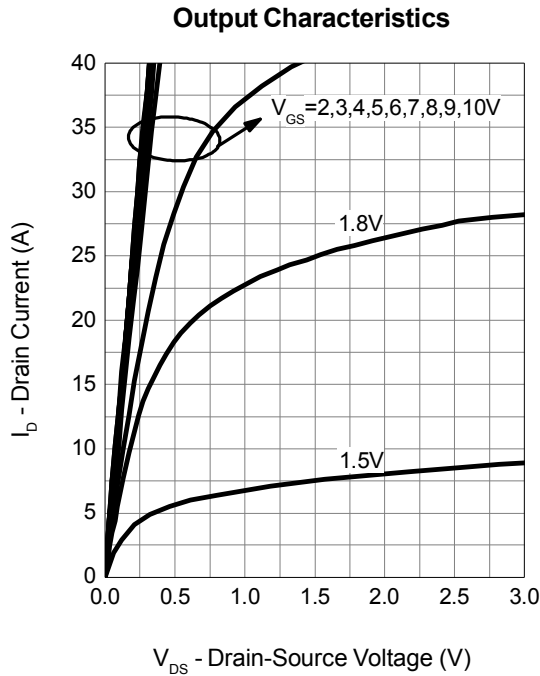
Note b : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

Note c : Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

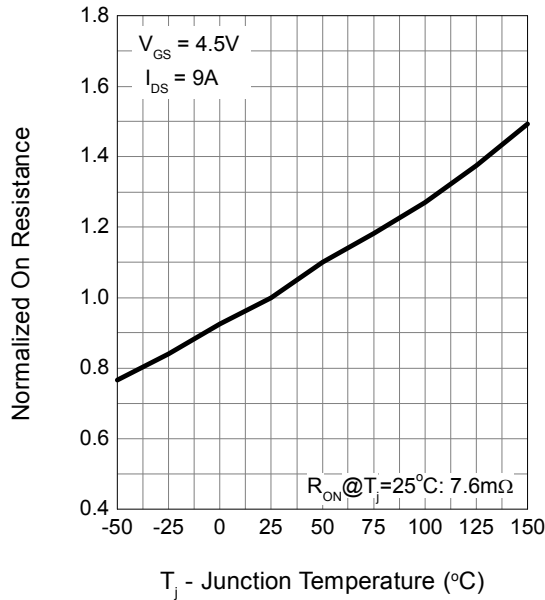


Typical Operating Characteristics (Cont.)

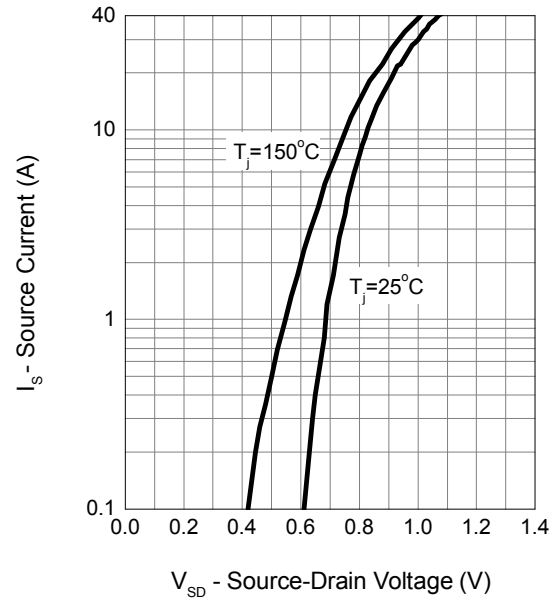


Typical Operating Characteristics (Cont.)

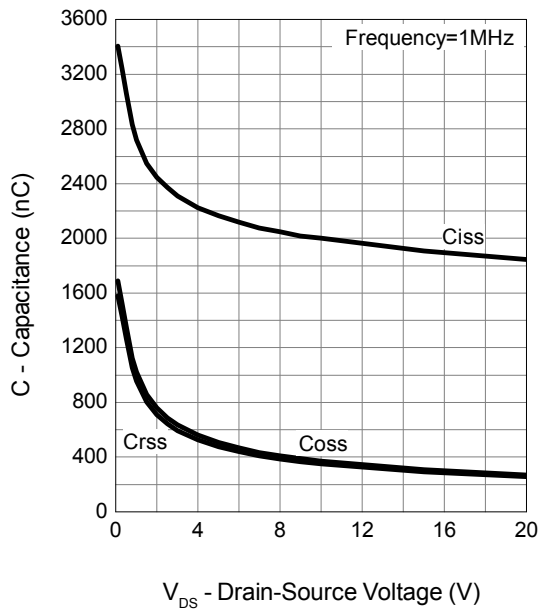
Drain-Source On Resistance



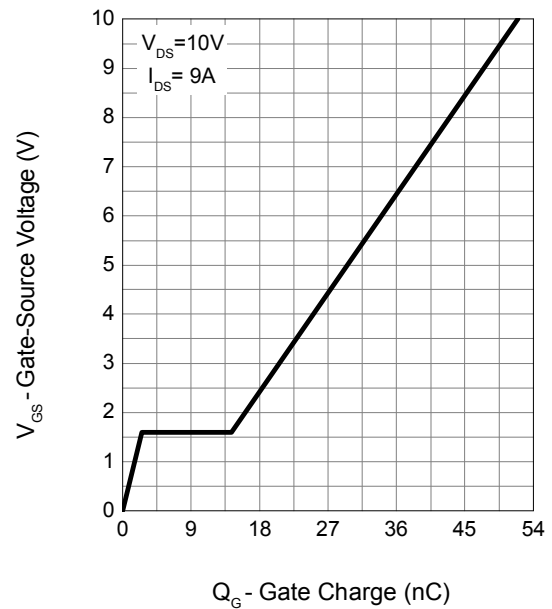
Source-Drain Diode Forward



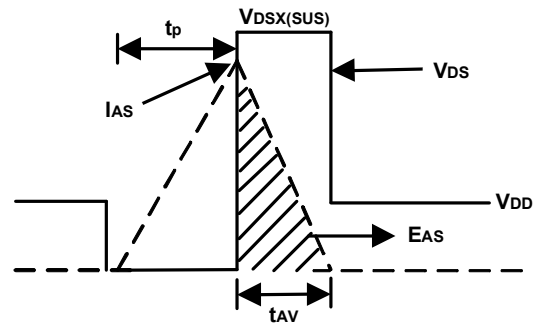
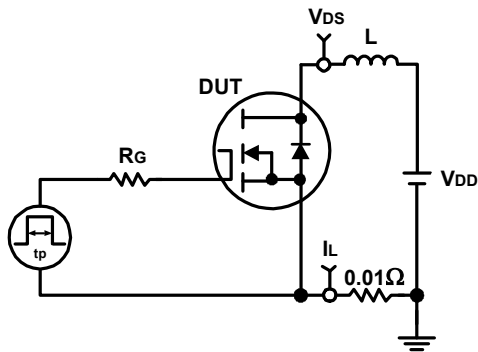
Capacitance



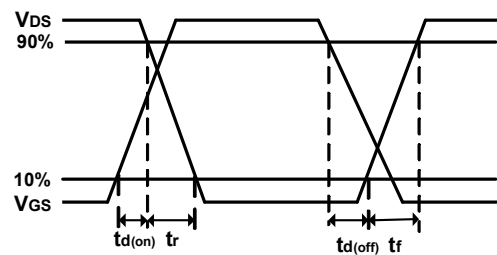
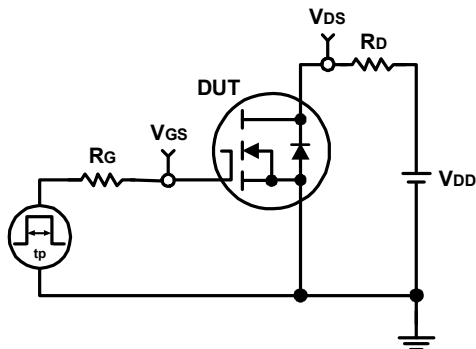
Gate Charge



Avalanche Test Circuit and Waveforms

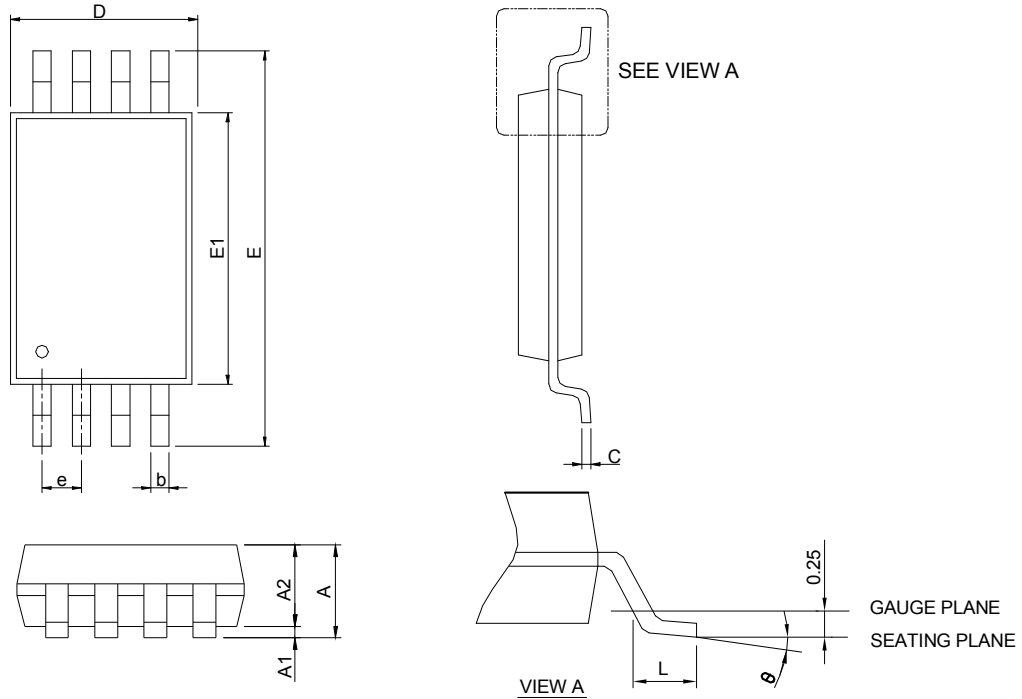


Switching Time Test Circuit and Waveforms



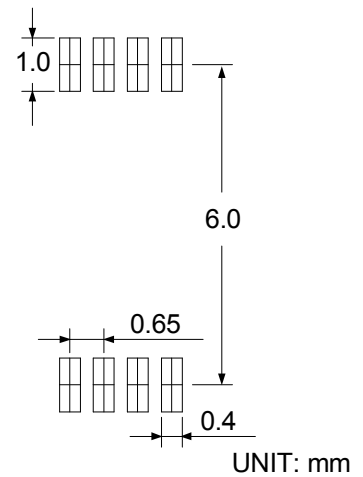
Package Information

TSSOP-8



SYMBOL	TSSOP-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	-	1.20	-	0.047
A1	0.05	0.15	0.002	0.006
A2	0.80	1.05	0.031	0.041
b	0.19	0.30	0.007	0.012
c	0.09	0.20	0.004	0.008
D	2.90	3.10	0.114	0.122
E	6.20	6.60	0.244	0.260
E1	4.30	4.50	0.169	0.177
e	0.65 BSC		0.026 BSC	
L	0.45	0.75	0.018	0.030
θ	0°	8°	0°	8°

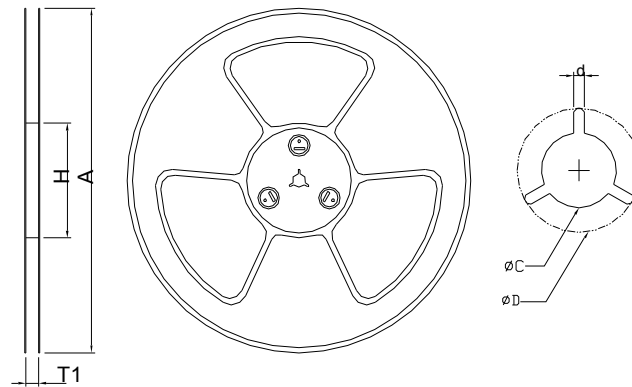
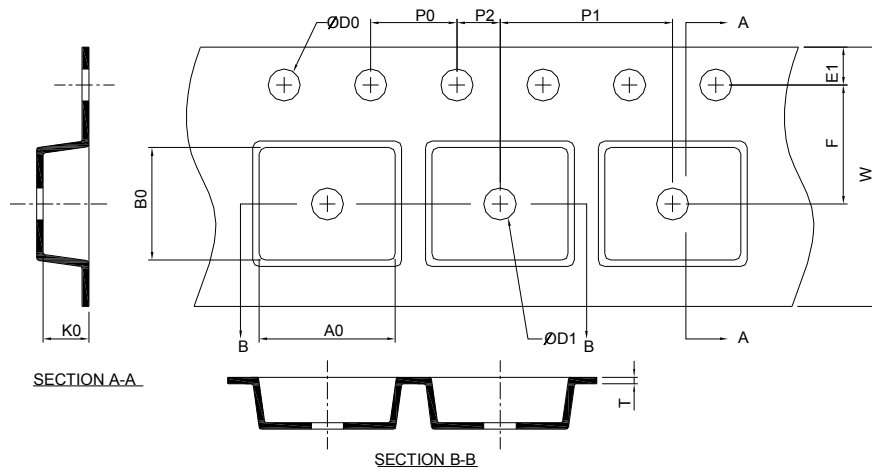
RECOMMENDED LAND PATTERN



Note : 1. Follow JEDEC MO-153 AA

2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "E1" does not include inter-lead flash or protrusions. Inter-lead flash and protrusions shall not exceed 10 mil per side.

Carrier Tape & Reel Dimensions

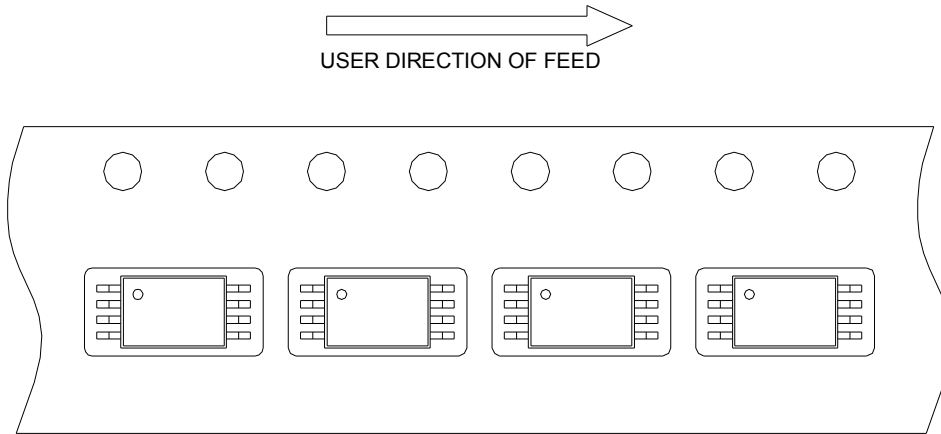


Application	A	H	T1	C	d	D	W	E1	F
TSSOP-8	330.0±2.00	50 MIN.	12.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	12.0±0.30	1.75±0.10	5.5±0.10
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.00±0.10	8.00±0.10	2.00±0.05	1.5+0.10 -0.00	1.5 MIN.	0.6+0.00 -0.40	6.90±0.20	3.40±0.20	1.60±0.20

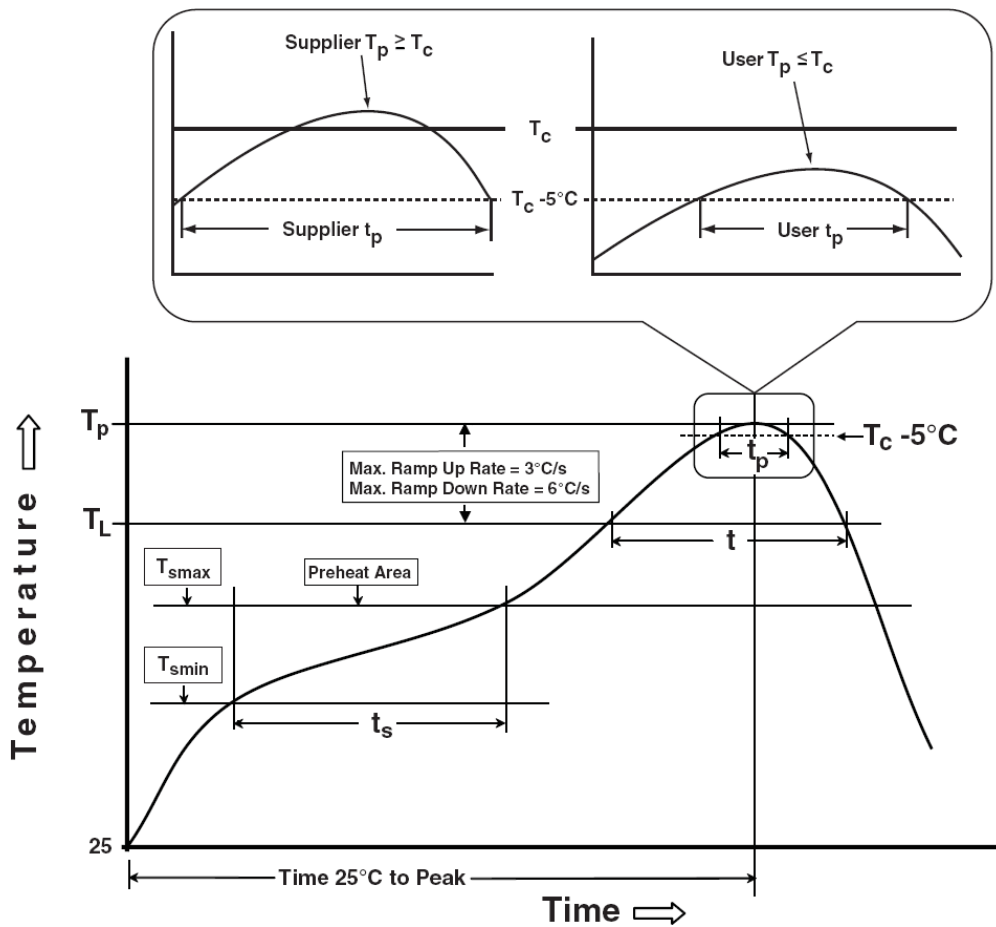
(mm)

Taping Direction Information

TSSOP-8



Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T_{smin})	100 °C	150 °C
Temperature max (T_{smax})	150 °C	200 °C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body Temperature (T_p)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_p)** within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds
Average ramp-down rate (T_p to T_{smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature (T_p) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, 80% of VDS max @ T_{jmax}
HTGB	JESD-22, A108	1000 Hrs, 100% of VGS max @ T_{jmax}
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

Customer Service

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